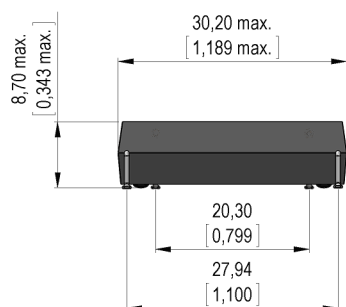
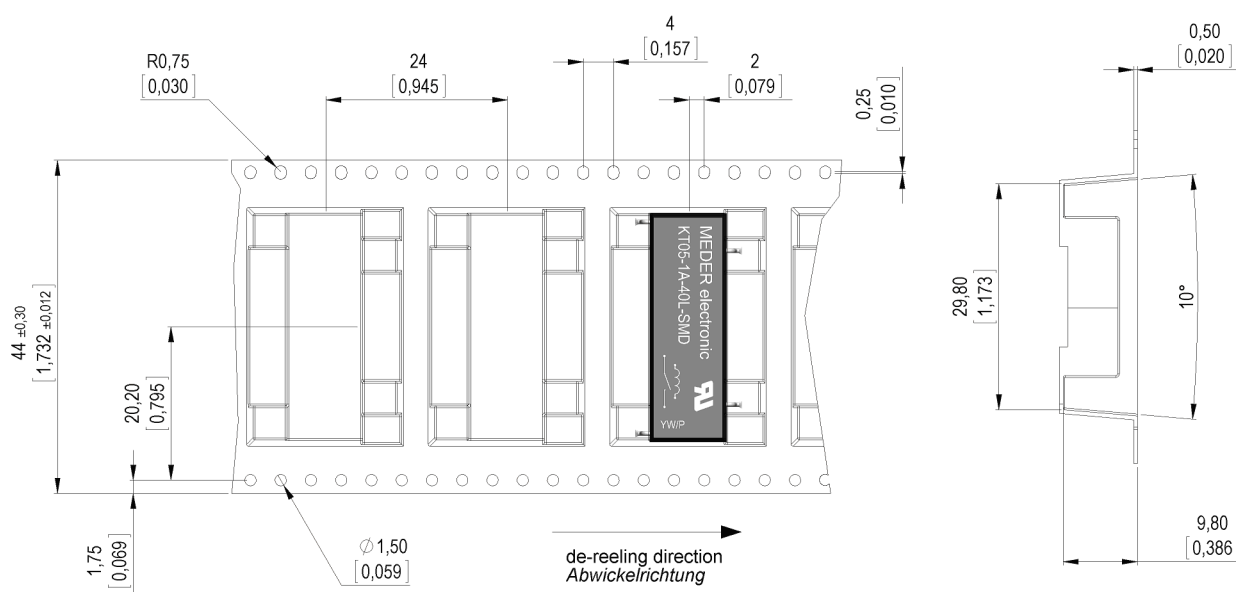
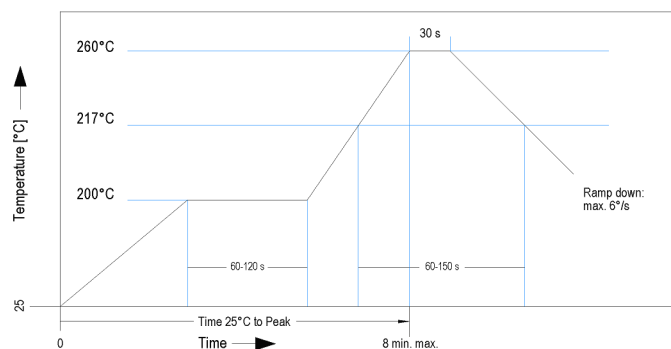


reflow soldering conditions according to JEDEC norm J-STD 020D.1



Coil Data at 20 °C	Conditions	Min	Typ	Max	Unit
Coil resistance		72	80	88	Ohm
Coil voltage			5		VDC
Rated power			313		mW
Thermal resistance			80		K/W
Inductance			21		mH
Pull-In voltage				3,5	VDC
Drop-Out voltage		0,55			VDC

Contact Data 85	Conditions	Min	Typ	Max	Unit
Contact rating	Any DC combination of V & A not to exceed their individual max.'s			100	W
Switching voltage	DC or Peak AC			1.000	V
Switching current	DC or Peak AC			1	A
Carry current	DC or Peak AC 100% Duty Cycle			2,5	A
Contact resistance static	Measured with 40% overdrive			150	mOhm
Contact resistance dynamic	Maximum value 1,5 ms after excitation			200	mOhm
Insulation resistance	RH <45 %, 100 V test voltage	10			GOhm
Breakdown voltage (40-50 AT)	according to EN 60255-5	3			kV DC
Capacitance	@ 10 kHz across open switch		0,5		pF

Special Product Data	Conditions	Min	Typ	Max	Unit
Dielectric Strength Coil/Contact	according to EN 60255-5	7			kV DC
Insulation resistance Coil/Contact	RH <45%, 200 VDC measuring voltage	1			TOhm
Capacity Coil/Contact	@ 10 kHz		1,2		pF
Housing material		mineral filled epoxy			
Approval		UL-File Nr. NRNT2.E156887			
Reach II / RoHS conformity		yes			

Environmental data	Conditions	Min	Typ	Max	Unit
Shock	1/2 sine, duration 11ms, in 3 axis			30	g
Vibration	from 10 - 2000 Hz			20	g
Ambient temperature		-40		100	°C
Storage temperature		-40		125	°C
Soldering Temperature Tsold	Reflow acc.IPC/JEDEC J-STD-020D.1			260	°C
Washability		fully sealed			

General data	Conditions	Min	Typ	Max	Unit
Packaging		T&R per 250 pcs.			